

### **AMC7135**

## Dtek www.addmtek.com

### **350mA Advanced Current Regulator**

#### DESCRIPTION

The AMC7135 is a low dropout current regulator rated for 350mA constant sink current. The low quiescent current and low dropout voltage is achieved by advanced Bi-CMOS process.

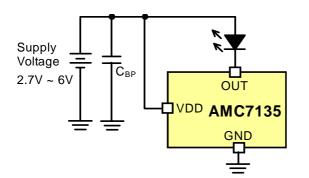
#### **FEATURES**

- 350mA constant sink current.
- Output short / open circuit protection.
- Low dropout voltage.
- Low quiescent current
- Supply voltage range  $2.7V \sim 6V$
- **2KV HBM ESD protection**
- Advanced Bi-CMOS process.
- SOT-89 and TO-252 package

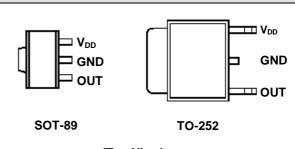
TYPICAL APPLICATION CIRCUIT

#### **APPLICATIONS**

PACKAGE PIN OUT



Power LED driver



(Top View)

ORDER INFORMATION						
т	PK	SOT-89	SJ	TO-252		
I <sub>OUT</sub>		3-pin	01	3-pin		
340-380mA		AMC7135PKF AMC7				
300-340mA		AMC7135PKFA	AMC7135SJFA			
<ul> <li>Note: 1. All surface-mount packages are available in Tape &amp; Reel. Append the letter "T" to part number (i.e. AMC7135PKFAT).</li> <li>2. The letter "F" is marked for Lead Free process.</li> <li>3. The letter "A" is marked for current ranking.</li> </ul>						



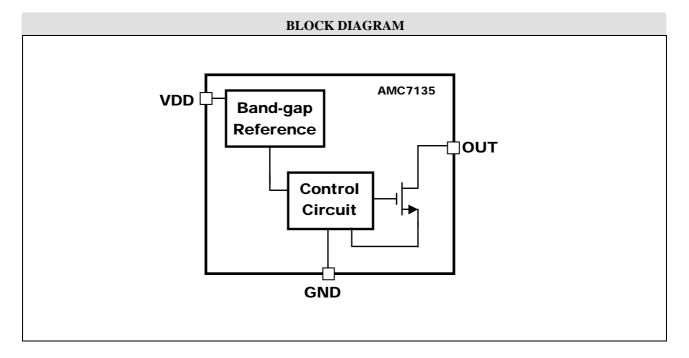
AMC7135

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#### ABSOLUTE MAXIMUM RATINGS (Note)

Input Voltage, V <sub>DD</sub>	-0.3V to 7V
Output Voltage, V <sub>OUT</sub>	-0.3V to 7V
Maximum Junction Temperature, T <sub>J</sub>	150°C
Storage Temperature Range	-40°C to 150°C
Lead Temperature (Soldering, 10 seconds)	260°C
Note: Exceeding these ratings could cause damage to the device. All voltages are with respect to Ground.	

Currents are positive into, negative out of the specified terminal.



#### PIN DESCRIPTION

Pin Name	Pin Function
V <sub>DD</sub>	Power supply.
OUT	Output pins. Connected to load.
GND	Ground.



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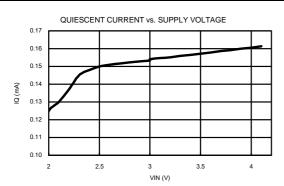
<b>RECOMMENDED OPERATING CONDITIONS</b>							
Parameter	Symbol	Min	Тур	Max	Unit		
Supply Voltage	V <sub>DD</sub>	2.7		6	V		
Output Sink Current	I <sub>OUT</sub>			400	mA		
Operating Free-air Temperature Range	T <sub>A</sub>	-40		+85	°C		

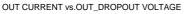
#### DC ELECTRICAL CHARACTERISTICS

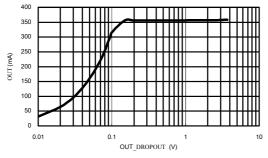
$V_{DD}$ =3.7V, T <sub>A</sub> =25°C, No Load, (Unless otherwise noted)							
Parameter	Symbol	Condition	Min	Тур	Max	Unit	Apply Pin
Ordered Sint Comment	I <sub>SINK</sub>	V <sub>OUT</sub> =0.2V	340	360	380	mA	
Output Sink Current		V <sub>OUT</sub> =0.2V, Rank A	300	320	340	mA	
Load Regulation		$V_{OUT}=0.2V$ to $3V$			3	mA/V	OUT
Line Regulation		$V_{DD}$ = 3V to 6V, $V_{OUT}$ =0.2V			3	mA/V	001
Output Dropout Voltage	V <sub>OUTL</sub>			120		mV	
Supply Current Consumption	I <sub>DD</sub>			200		uA	VDD
		00 X					

Note 1: Output dropout voltage: 90% x I<sub>OUT</sub> @ V<sub>OUT</sub>=200mV

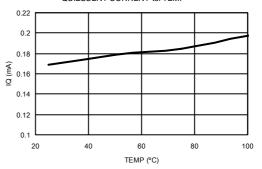
#### TYPICAL OPERATION CHRACTERISTICS







QUIESCENT CURRENT vs. TEMP



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### AMC7135

**APPLICATION INFORMATION** 

#### The Maximum Power Dissipation on Regulator:

 $P_{D(MAX)} = V_{OUT(MAX)} \times I_{OUT(NOM)} + V_{IN(MAX)} \times I_Q$ 

 $V_{OUT(MAX)}$  = the maximum voltage on output pin;

 $I_{OUT(NOM)}$  = the nominal output current;

 $I_Q$  = the quiescent current the regulator consumes at  $I_{OUT(MAX)}$ ;

 $V_{IN(MAX)}$  = the maximum input voltage.

#### **Thermal Consideration:**

The maximum junction temperature ratings of AMC7135 should not be exceeded under continuous normal load conditions. When power consumption is over about 700mW (SOT-89 package, at  $T_A=70^{\circ}$ C) or 1000mW (TO-252 package, at  $T_A=70^{\circ}$ C), additional heat sink is required to control the junction temperature below 120°C.

The junction temperature is:

 $T_{J} = P_{D} \left( \theta_{JT} + \theta_{CS} + \theta_{SA} \right) + T_{A}$ 

P<sub>D</sub> : Dissipated power.

 $\theta_{\rm JT:}$  Thermal resistance from the junction to the mounting tab of the package.

 $\theta$  <sub>CS</sub>: Thermal resistance through the interface between the IC and the surface on which it is mounted.

(typically,  $\theta_{\rm CS} < 1.0^{\circ} {\rm C/W}$ )

 $\theta_{SA}$ : Thermal resistance from the mounting surface to ambient (thermal resistance of the heat sink).

If PC Board copper is going to be used as a heat sink, below table can be used to determine the appropriate size of copper foil required. For multi-layered PCB, these layers can also be used as a heat sink. They can be connected with several through-hole vias.

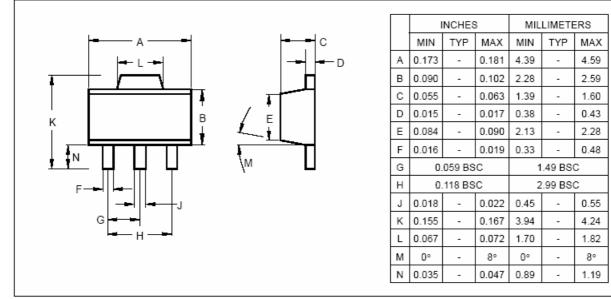
PCB $\theta$ sa (°C/W)	59	45	38	33	27	24	21
PCB heat sink size (mm <sup>2</sup> )	500	1000	1500	2000	3000	4000	5000



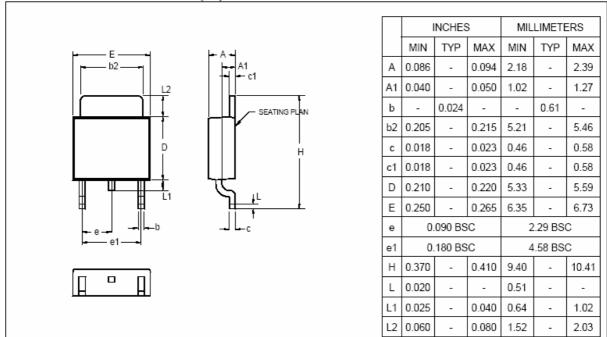
### AMC7135

#### PACKAGE

#### 3-Pin Surface Mount SOT-89



#### 3-Pin Surface Mount TO-252 (SJ)







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